ML

Introduction

ML is an IPC Grade 3, low profile, controlled elongation copper foil designed specifically for multilayer applications. ML foil is supplied with a TOB treatment which is fully compatible with all epoxy resin systems.

Benefits

- Low profile for finer lines and consistent etching
- Decreased foil treatment residues after etching
- Controlled %E @ 180°C for consistent drilling
- HTE characteristics eliminates inner layer foil cracking

Typical Physical Characteristics

Oak-Mitsui foils meet all requirements of IPC-4562 and are produced with the patented "AT" resin resistant treatment.

Nominal Thickness Area Weight		microns oz/ft²	9 * 1/4	12 ** 3/8	18 1/2	35 1
Tensile	ambient 180°C	Kpsi Kpsi	77.5 35	60 30	60 30	55 30
Elongation	ambient 180°C	%E %E	4.5 7	8 8	8 8	15 8
Roughness	drum matte	Ra Rmax	9 164	10 150	10 200	10 300
Peel Strength B Epoxy, Tg 170°C	matte	lbs/in	6.0	6.5	7.5	10.5

Mitsui supplied material, * 3EC, ** MWU III

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